

# MA151K, MA152K

Silicon Epitaxial Planar Type

Switching

■ Features

- Fast  $t_{rr}$
- Small  $C_t$

■ Absolute Maximum Ratings ( $T_a=25^\circ\text{C}$ )

Item	Symbol	Value	Unit
Reverse Voltage (DC)	MA151K	40	V
	MA152K	80	
Peak Reverse Voltage	MA151K	40	V
	MA152K	80	
Forward Current (DC)	$I_F$	100	mA
Peak Forward Current	$I_{FM}$	225	mA
Non-Repetitive Peak Forward Surge Current	$I_{FSM}^*$	500	mA
Junction Temperature	$T_j$	150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-55 ~ +150	$^\circ\text{C}$

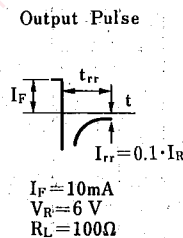
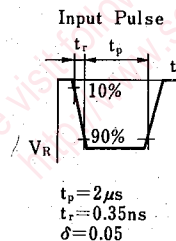
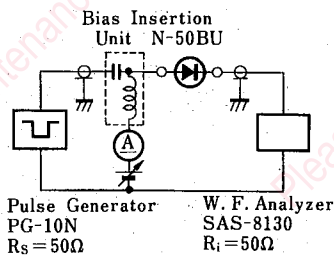
\* $t=1s$

■ Electrical Characteristics ( $T_a=25^\circ\text{C}$ )

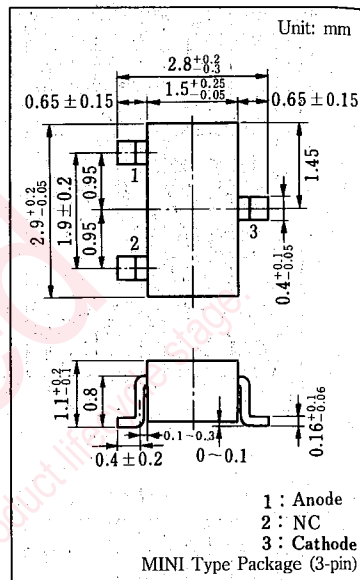
Item	Symbol	Condition	min.	typ.	max.	Unit
Reverse Current (DC)	MA151K	$V_R=35\text{ V}$			0.1	$\mu\text{A}$
	MA152K	$V_R=75\text{ V}$			0.1	
Forward Voltage (DC)	$V_F$	$I_F=100\text{ mA}$	0.95		1.2	V
Reverse Voltage (DC)	MA151K	$I_R=100\ \mu\text{A}$	40			V
	MA152K		80			
Terminal Capacitance	$C_t$	$V_R=0, f=1\text{ MHz}$		0.9	2	pF
Reverse Recovery Time	$t_{rr}^*$	$I_F=10\text{ mA}, V_R=6\text{ V}, R_L=100\ \Omega$ $I_{Rr}=0.1 \cdot I_R$			3	ns

© Input and output frequency of ratings: 100MHz

\* $t_{rr}$  measuring circuit



■ Package Dimensions



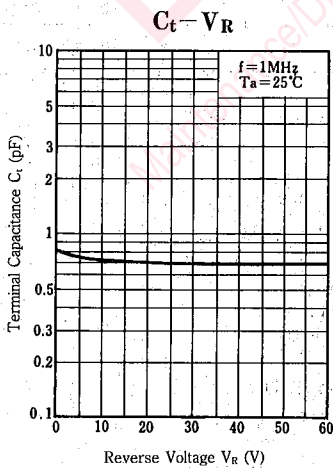
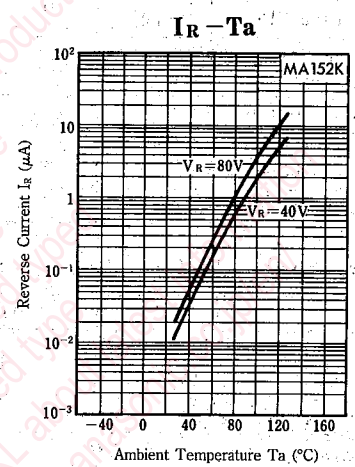
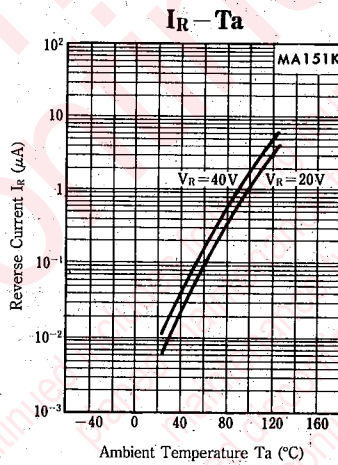
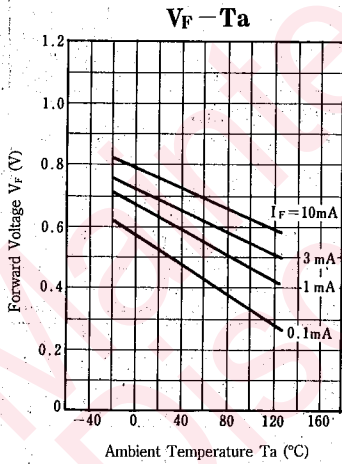
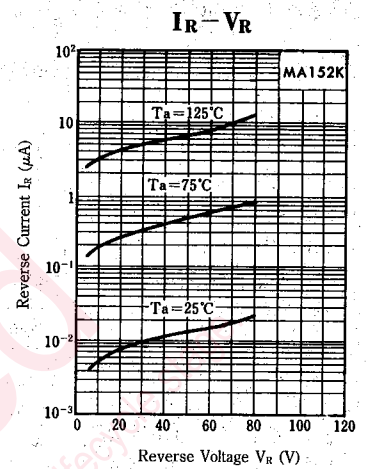
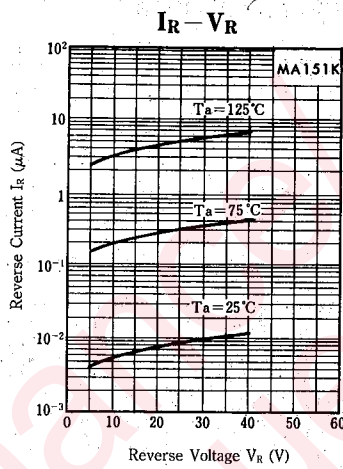
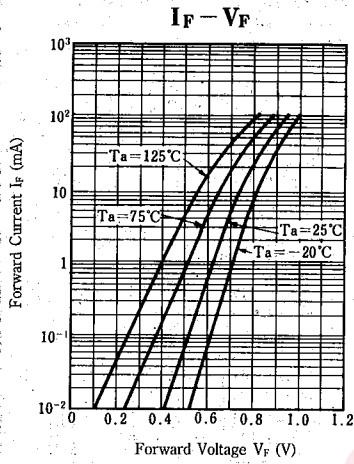
■ Marking Symbol

Type No.	MA151K	MA152K
Symbol	MH	MI

■ Marking Symbol (Ex.)



(MA151K)



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